IPC ASSOCIATION ELECTRONICS	Material Con © Copyright 2005 international and	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					rials and N	ials and Mfg Information			
upplier	Information														
Company name*				Company unique ID			Unique ID Authority					Response Date*			
nsemi											2023-0	2023-06-08			
Contact Na	me	Title - Contact			I	Phone - Contact*				Email ·	Email - Contact*				
Product-E1	nv-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized	Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-E	nv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		m Number Mfr Item Name				Effective Date Version Manufacturing Sit		Manufacturing Site		Weight*	UOM	Unit Type		
		LC75832WS-E LCD Display Driver		er		2023-06-08		PHM			400.0	mg	Each		
Ianufact	turing Proccess Inforn	nation													
Т	Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperatu		ire Max Time at Peal	k Tempera	ture Numb	er of Reflow Cyc	eles		
contains Bi			CU Alloy 3				260 C 30			seconds 3					
omments															
LIENTIC	ON: MSL 3 Rated item requ	ires Bake and D	Ory Pack (afte	r electrical test)											
or more in	nformation regarding mater	ial composition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and corrections that such information is true and correction that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.98	mg	Supplier	Silicon (Si)	7440-21-3		4.9491	mg
			Supplier	Polyimide	Proprietary Data		0.0309	mg
Die Attach	1.05	mg	Supplier	Silver (Ag)	7440-22-4		0.7144	mg
			Supplier	Epoxy resins	129915-35-1		0.3037	mg
			Supplier	Other Metal Oxide	Proprietary Data		0.0229	mg
			В	Antimony Pentoxide (Sb2O5)	1314-60-9		0.009	mg
Lead Frame	237.41	mg	Supplier	Silver (Ag)	7440-22-4		1.282	mg
			Supplier	Zinc (Zn)	7440-66-6		0.4511	mg
			Supplier	Iron (Fe)	7439-89-6		6.1252	mg
			Supplier	Copper (Cu)	7440-50-8		229.2194	mg
			Supplier	Phosphorus (P)	7723-14-0		0.3324	mg
Mold Compound-Black	150.84	mg		Epoxy Phenol Resin	proprietary data		21.1176	mg
			Supplier	Carbon Black (C)	1333-86-4		0.7542	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		128.214	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.7542	mg
Plating	4.2	mg	В	Bismuth (Bi)	7440-69-9		0.0252	mg
			Supplier	Tin (Sn)	7440-31-5		4.1748	mg
Wire Bond - Au	1.52	mg	Supplier	Gold (Au)	7440-57-5		1.52	mg